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With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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HiPerFET™ Power MOSFETs IXFR 180N10 ISOPLUS247™

(Electrically Isolated Back Surface)

Single MOSFET Die

Preliminary data



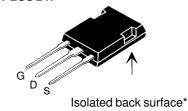
 $t_{rr} \leq 250 \text{ ns}$

Symbol	Test Conditions	Maximum Ratings		
V _{DSS}	$T_J = 25^{\circ}\text{C to } 150^{\circ}\text{C}$ $T_J = 25^{\circ}\text{C to } 150^{\circ}\text{C}; R_{GS} = 1 \text{ M}\Omega$	100 100	V	
V _{GS} V _{GSM}	Continuous Transient	±20 ±30	V	
I _{D25} I _{D(RMS)} I _{DM}	$T_{\rm C}=25^{\circ}{\rm C}$ (MOSFET chip capability) External lead (current limit) $T_{\rm C}=25^{\circ}{\rm C}$, Note 1 $T_{\rm C}=25^{\circ}{\rm C}$	165 76 720 180	A A A	
E _{AR} E _{AS}	T _C = 25°C T _C = 25°C	60 3	mJ J	
dv/dt	$\begin{array}{l} I_{_{S}} & \leq I_{_{DM}},di/dt \leq 100A/\mu s,V_{_{DD}} \leq V_{_{DSS}} \\ T_{_{J}} & \leq 150^{\circ}C,R_{_{G}} = 2\Omega \end{array}$	5	V/ns	
P _D	T _C = 25°C	400	W	
T _J T _{JM} T _{stg}		-55 +150 150 -55 +150	°C °C °C	
T _L	1.6 mm (0.063 in.) from case for 10 s	300	°C	
V _{ISOL}	50/60 Hz, RMS t = 1 min	2500	V~	
Weight		5	g	

E _{AR}	T _C = 25°C			60	mJ		
E _{AS}	$T_{\rm C}^{\circ} = 25^{\circ}{\rm C}$			3	J		
dv/dt	$\begin{array}{ll} I_{_{S}} & \leq I_{_{DM}},di/dt \leq 100\;A/\mu s,\\ T_{_{J}} & \leq 150^{\circ}C,R_{_{G}} = 2\;\Omega \end{array}$	$V_{DD} \le V_{DSS}$		5 V	//ns		
P _D	T _C = 25°C		4	.00	W		
T, T _{JM}		-	55 +1	50	°C		
T _{.im}			1	50	°C		
T _{stg}		-	55 +1	50	°C		
T _L	1.6 mm (0.063 in.) from ca	se for 10 s	3	00	°C		
V _{ISOL}	50/60 Hz, RMS t = 1 mi	n	25	000	V~		
Weight				5	g		
Symbol	Test Conditions		Characteristic Value (T _J = 25°C, unless otherwise specified min. typ. max.				
V	V 0.V 1 2mA		.,,,,		V		
V _{DSS}	$V_{GS} = 0 \text{ V}, I_D = 3\text{mA}$	100			٧		
$V_{GS(th)}$	$V_{DS} = V_{GS}$, $I_{D} = 8mA$	2.0		4.0) V		

Symbol	Test Conditions	Characteristic Values (T _J = 25°C, unless otherwise specified) min. typ. max.			
V _{DSS}	$V_{GS} = 0 \text{ V}, I_D = 3\text{mA}$	100		V	
V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = 8mA$	2.0		4.0 V	
I _{GSS}	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0$			±100 nA	
I _{DSS}	$V_{DS} = V_{DSS}$ $V_{GS} = 0 V$	T _J = 25°C T _J = 125°C		100 μA 2 mA	
R _{DS(on)}	$V_{GS} = 10 \text{ V}, I_{D} = 90\text{A}$ Note 1			8 mΩ	

ISOPLUS 247™



G = Gate D = Drain S = Source

* Patent pending

Features

- · Silicon chip on Direct-Copper-Bond substrate
- High power dissipation
- Isolated mounting surface
- 2500V electrical isolation
- Low drain to tab capacitance(<25pF)
- Low $R_{DS (on)} HDMOS^{TM} process$
- Rugged polysilicon gate cell structure
- Unclamped Inductive Switching (UIS) rated
- · Fast intrinsic Rectifier

Applications

- · DC-DC converters
- · Battery chargers
- · Switched-mode and resonant-mode power supplies
- DC choppers
- · AC motor control

Advantages

- · Easy assembly
- · Space savings
- · High power density



Symbol	Test Conditions	Characteristic Values $(T_J = 25^{\circ}C, \text{ unless otherwise specified})$ min. typ. max.				
g _{fs}	$V_{DS} = 10 \text{ V}; I_{D} = 90 \text{A}$	Note 2	60	90		S
C _{iss} C _{oss} C _{rss}		, f = 1 MHz		9400 3200 1660		pF pF pF
t _{d(on)} t _r t _{d(off)}	$\begin{cases} V_{GS} = 10 \text{ V}, V_{DS} = 0.5 \\ R_{G} = 1 \Omega \text{ (External)}, \end{cases}$	• V _{DSS} , I _D = 90A		50 90 140 65		ns ns ns
$egin{aligned} oldsymbol{Q}_{g(on)} \ oldsymbol{Q}_{gs} \ oldsymbol{Q}_{gd} \end{aligned}$	$V_{GS} = 10 \text{ V}, V_{DS} = 0.5$	• V _{DSS} , I _D = 90A		400 65 220		nC nC nC
R _{thJC}				0.15	0.30	K/W K/W

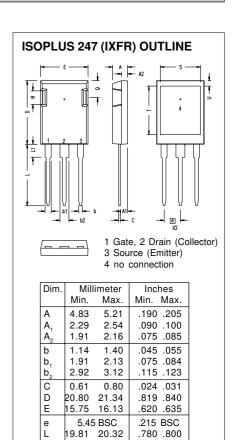
Source-Drain Diode		Characteristic Values (T ₁ = 25°C, unless otherwise specified)			
Symbol	Test Conditions	min.	typ.	max.	
I _s	V _{GS} = 0 V			180	Α
I _{SM}	Repetitive; pulse width limited by T_{JM}			720	Α
V _{SD}	$I_F = 100A, V_{GS} = 0 V, Note 1$			1.5	V
t _{rr})			250	ns

Note: 1. Pulse width limited by T_{JM}

 \mathbf{Q}_{RM}

2. Pulse test, $t \le 300 \ \mu s$, duty cycle $d \le 2 \%$

 $I_{_F} = 50\text{A}, \text{-di/dt} = 100 \text{ A/}\mu\text{s}, \text{ V}_{_{\text{R}}} = 100 \text{ V}$



L1

Q

R

S

μС

Α

1.1 13 3.81

5.59

4.32

13.21

15.75

4.32

6.20

4.83

13.72

3.03

16.26

.150 .170

.220 .244

.170 .190

.520 .540

.620 .640

.065 .080